

IN THE CLAIMS:***1-5. (cancelled)***

6. **(new)** A test assembly for an integrated circuit package, the test assembly comprising: a package substrate having a plurality of first contact pads adapted for receiving solder bumps and a plurality of first conductors connecting selected pairs of said first contact pads; and a test board having a plurality of second contact pads, a pair of major test pads, a plurality of minor test pads connected to selected ones of said second contact pads, and a plurality of second conductors connecting selected pairs of the second contact pads, wherein all of the second contact pads are divided into a plurality of groups such that all of the second contact pads in the same group are arranged in a line,

wherein, when the package substrate is mounted on the test board with each of said solder bumps soldered to one of the first contact pads and one of the second contact pads,

all of the pairs of connected second contact pads and the corresponding pairs of connected first contact pads form a conductive path that passes through all of the solder bumps,

each of said groups of connected second contact pads and the corresponding connected first contact pads form a closed circuit through all of the solder bumps therebetween when said major test pads are probed, and

when one pair of the minor test pads is probe, only one of said groups of the second contact pads and the corresponding connected first contact pads form another closed circuit through all of the solder bumps therebetween.

7. **(new)** The test assembly as claimed in claim 6, wherein all of the second contact pads belong to the closed circuit when the major test pads are probed.

8. **(new)** The test assembly as claimed in claim 6, wherein the package substrate is a ball grid array substrate.